

Part Number: L-138A8QMP/1GD

Green

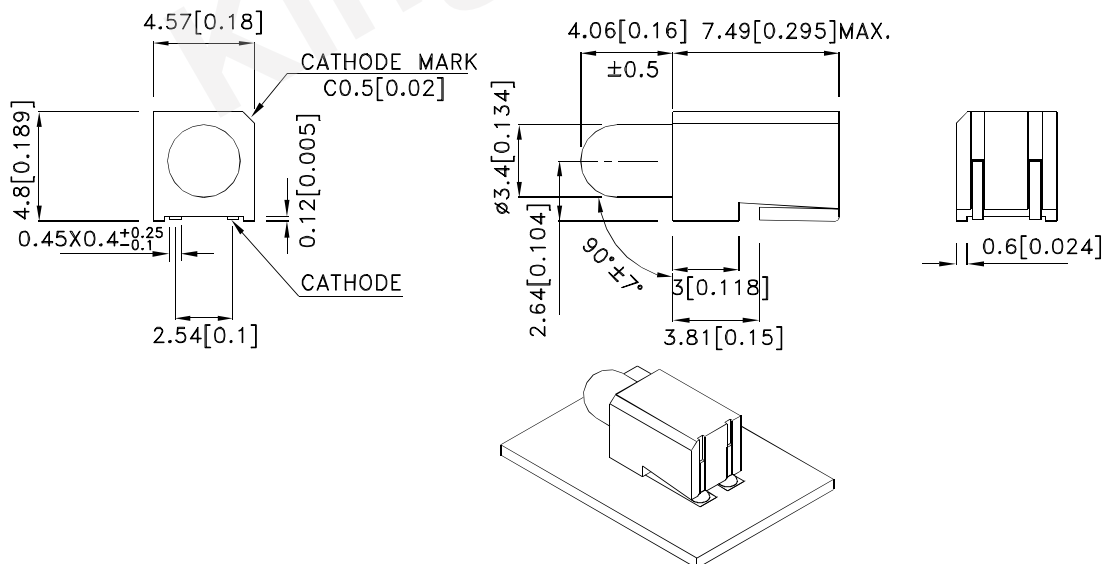
Features

- Surface mount type.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Package: 1000pcs / reel.
- Moisture sensitivity level : level 3.
- Housing UL rating: 94V-0.
- Housing material: PPA.
- High temperature resistant housing.
- High glass transition temperature epoxy.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-138A8QMP/1GD	Green (GaP)	Green Diffused	6	12	60°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
C	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.2	2.5	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR = 5V

Notes:

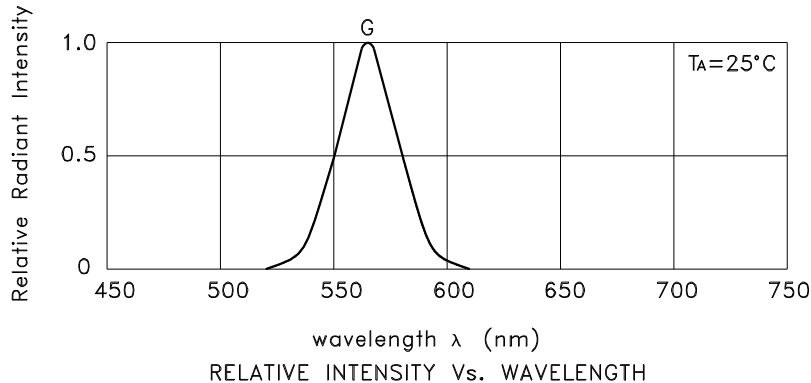
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

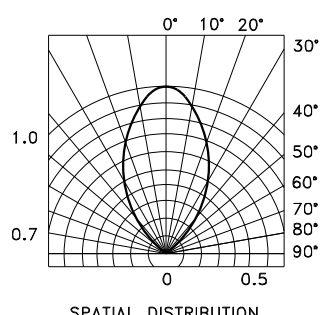
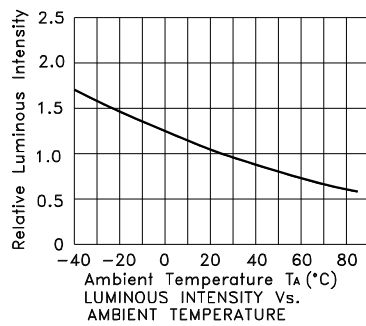
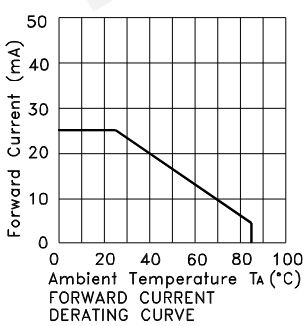
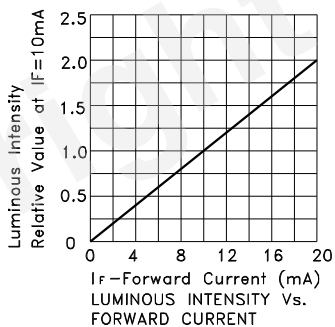
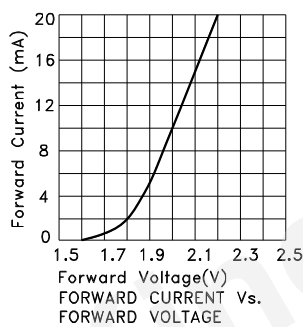
Parameter	Green	Units
Power dissipation	62.5	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

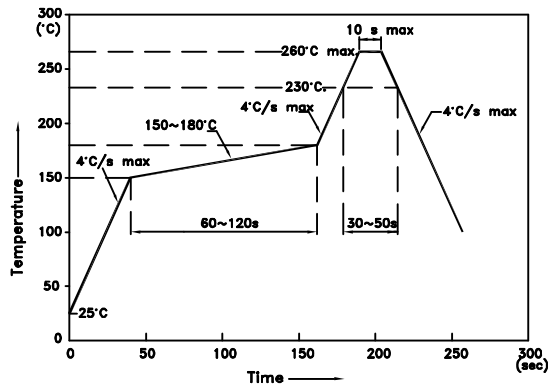


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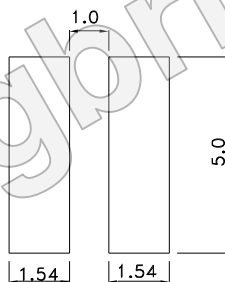
Reflow Soldering Profile For Lead-free SMT Process.



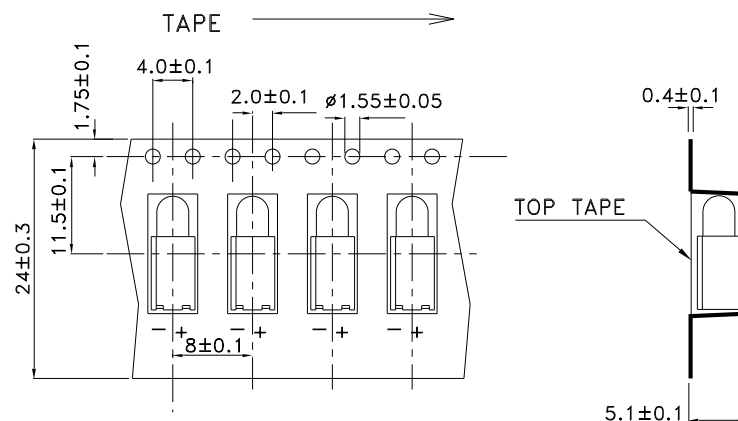
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. No more than once.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

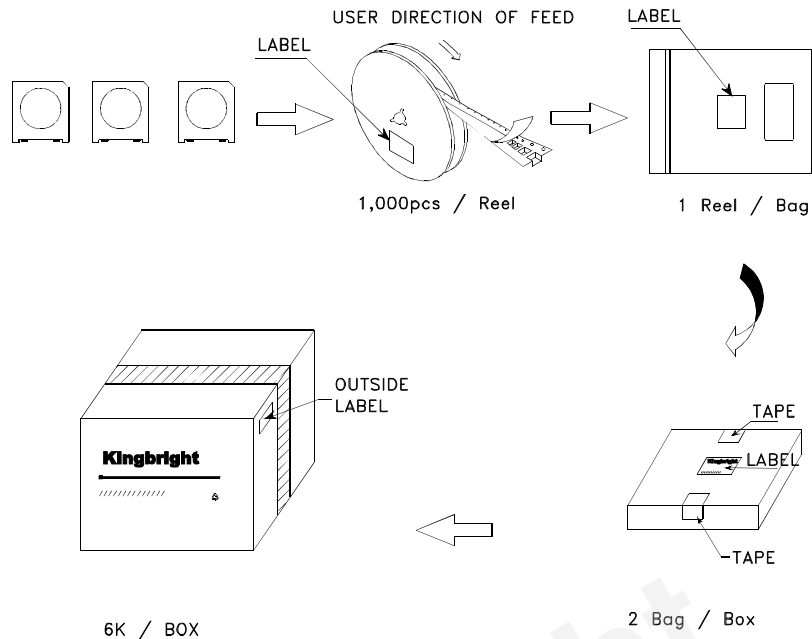



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

L-138A8QMP/1GD



Kingbright	
P/NO: L-138A8QMPxxx	
QTY: 1000 pcs	Q.C. Q C XX XX XX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
	
RoHS Compliant	

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PRECAUTIONS

- 1.A moisture barrier bag (MBB) containing LEDs shall be kept in an environment with temperature below 40°C and humidity below 90% RH.
A MBB shall be kept sealed until the LEDs contained in that bag are to be used immediately. Storage in an environment with temperature 5~30°C and humidity below 60% RH.
- 2.After a MBB has been opened, all LEDs contained in that bag shall complete soldering process within according to the conditions listed on the Kingbright MBB.
- 3.If the 10% spot of a humidity indicator card (HIC) indicates wet , LEDs shall be baked according to the conditions listed on the Kingbright MBB.
- 4.During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 5.The tip of the soldering iron should never touch the lens epoxy.
- 6.After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
- 7.If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.